

**Amendments to the claims are as follows:**

1. (Currently Amended) An electronic circuit unit comprising:
  - a substrate on which a wiring pattern is provided;
  - electronic parts, including a semiconductor bare chip disposed on the surface of the substrate;
  - a soft sealing resin provided on the surface of the substrate so as to cover the electronic parts, wherein a wire of the semiconductor bare chip is connected to the wiring pattern and is covered with the soft sealing resin;
  - and
  - a protection member made of a resin harder than the soft sealing resin having an upper wall which is a flat outer surface and leg parts extending from the upper wall to the substrate, wherein the ~~protection member is provided with~~ the leg parts which are secured to the substrate while covering the sealing resin.
2. (Original) The electronic circuit unit according to Claim 1, wherein the protection member covers the entire exposed surface of the substrate and the entire outer surface of the soft sealing resin.
3. (Currently Amended) The electronic circuit unit according to Claim 1, wherein the substrate comprises at least one of an inductor formed of a thin film, a resistor formed of a thin film, and/or a capacitor formed of a thin film thereon.
4. (Currently Amended) A method of manufacturing an electronic circuit unit, the method comprising ~~the steps of~~:
  - preparing a substrate on which electronic parts including a semiconductor bare chip are provided and a sealing resin composed of a soft resin material covering the electronic parts is provided; and

forming a protection member by filling or coating a resin that becomes harder than the sealing resin when solidifying, on ~~a~~the surface of the substrate and ~~an~~the outer surface of the sealing resin so as to cover the surface of the substrate and the outer surface of the sealing resin,

wherein the protection member is provided with an upper wall having a flat outer surface and leg parts extending from the upper wall and secured to the substrate.

5. The method according to Claim 4, further comprising providing a large plate substrate that is formed by bonding a plurality of the substrates on which the sealing resin is formed,

wherein the resin that becomes harder than the sealing resin is filled or coated on the surface of the large plate substrate and the sealing resin, and the large plate substrate and the resin are cut after the resin is solidified, thereby forming a single substrate having the protection member.